

# SLOTOCOUP PRT 150脉冲电镀

## 高速脉冲电镀系统

High depositu in speed / High current Reverse Pulse Plating technology

在高堆叠层数的伺服器和通讯PCB主板制造中,选择合适的电镀添加剂至关重要。SLOTOCOUP PRT 150 为您带来前所未有的制程优势

It is crucial to select the correct electrolyte additive system in higher layer counts for the PCB process, especially for the server and communications market.

**高效生产:** 支持高电流密度操作同时维持出色的通孔贯孔能力,让生产更高效。

Efficient production: supporting high ASD production and outstanding TP performance to increase production efficiency.

**精准均匀:** 铜厚分布均匀缩小不同孔径之间的铜厚差异,杜绝孔内偏边问题。

Uniform distribution: minimum copper THK deviation for each TH design on PCB and eliminates uneven THK effect inside TH.

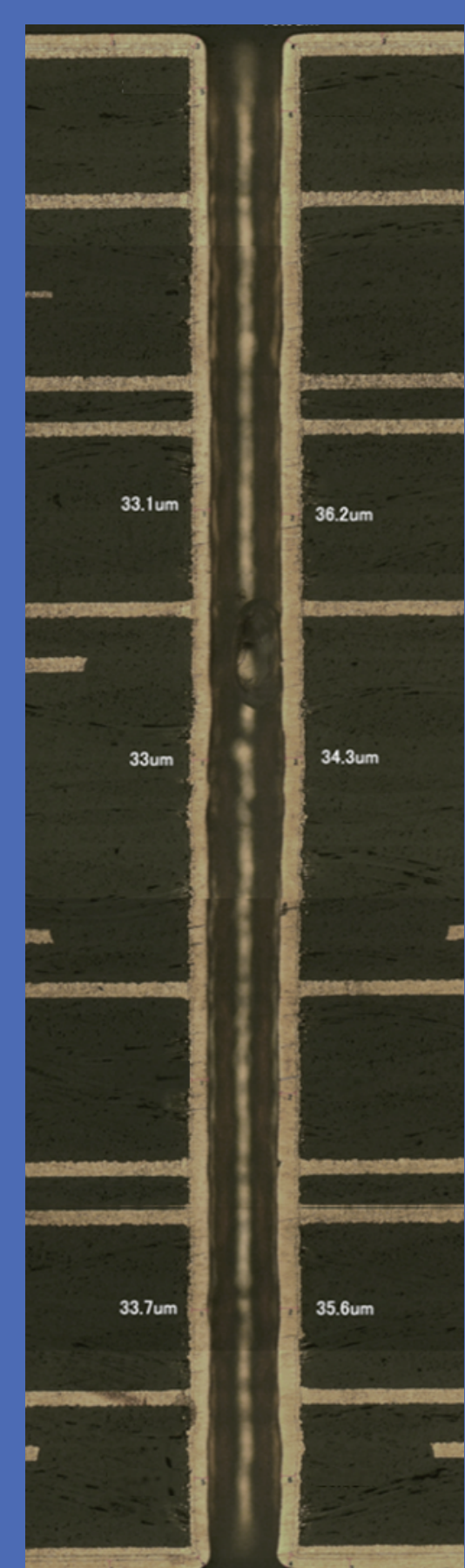
将能有效降低电镀铜厚需求,实现产品良率、成本与品质的三重提升。

Able to control minimum copper requirement. Elevating product yield rate, cost and quality.

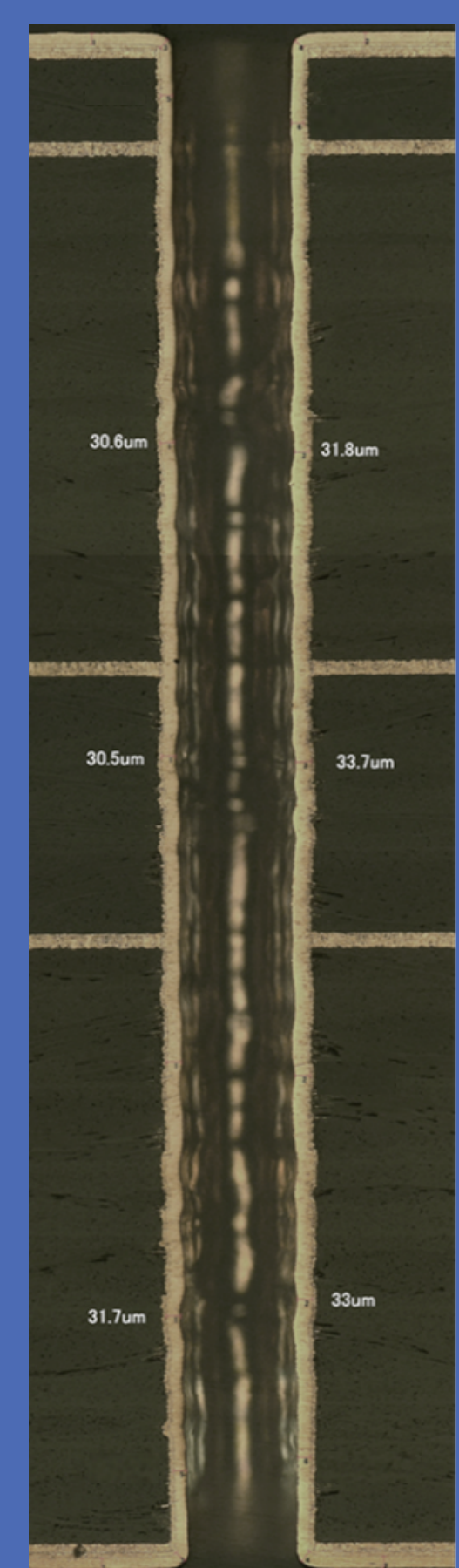
## 产品优势 Benefits

均匀的孔内铜厚分布

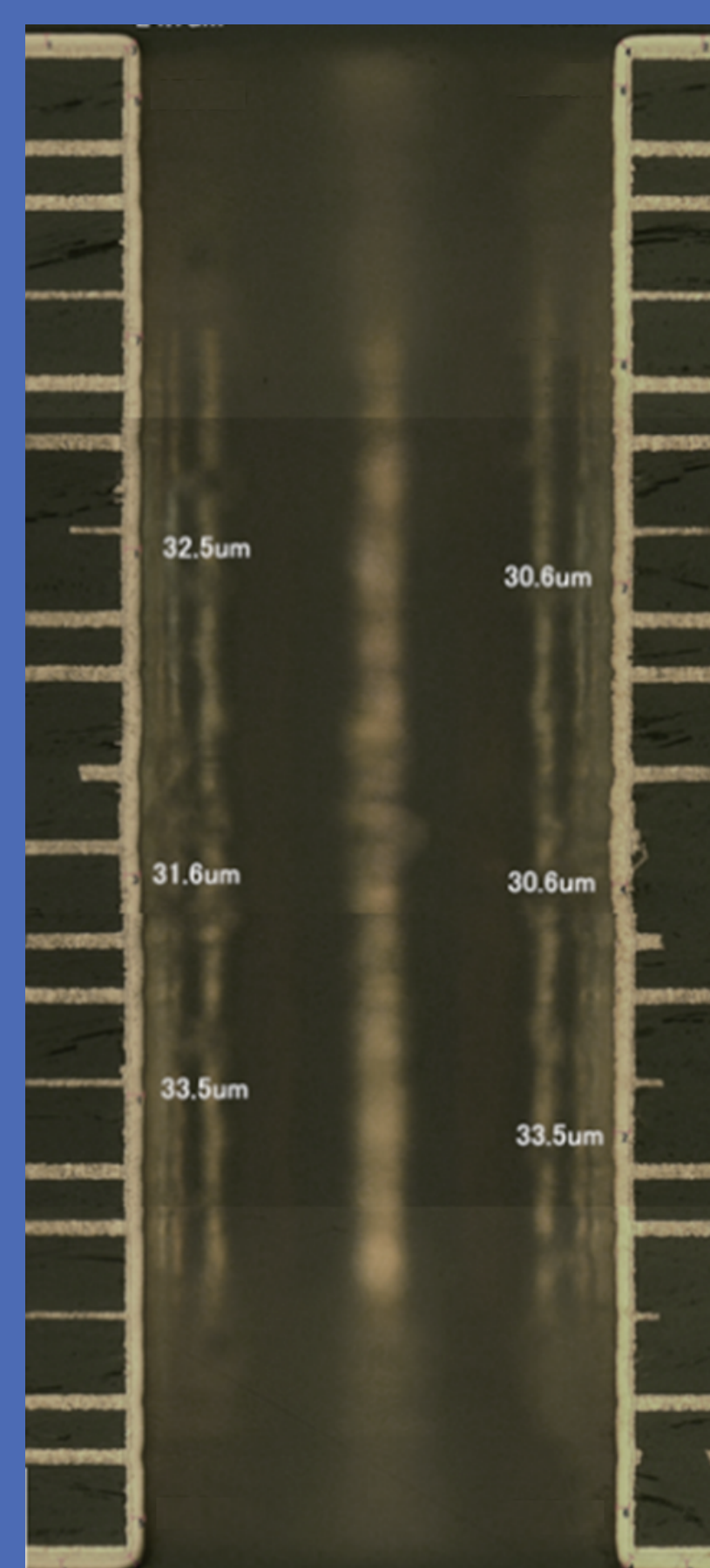
Uniform copper distribution in TH



Ø 0.20mm (AR 16)  
TP 140%



Ø 0.25mm (AR 13)  
TP 131%



Ø 1.1mm (AR 3)  
TP 129%

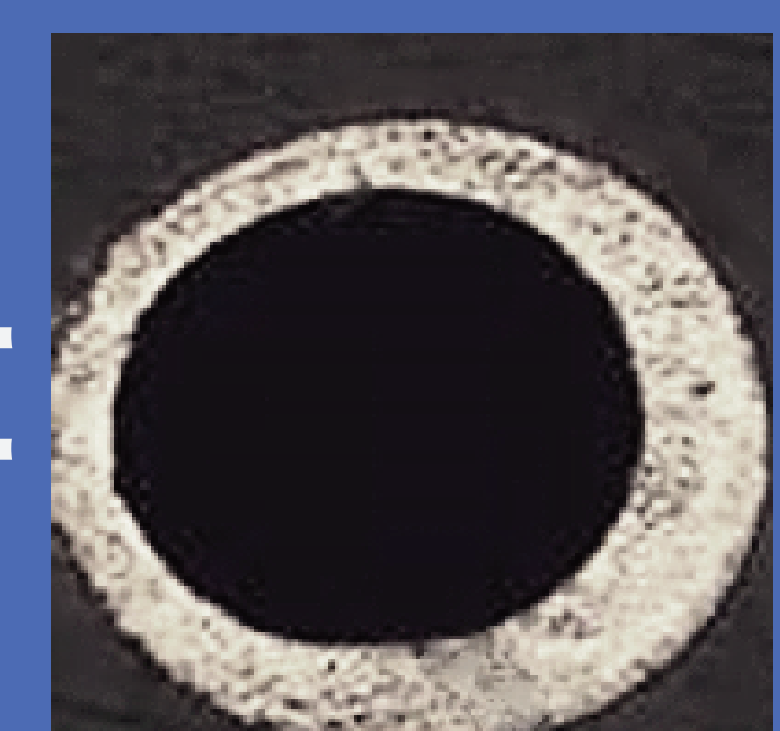
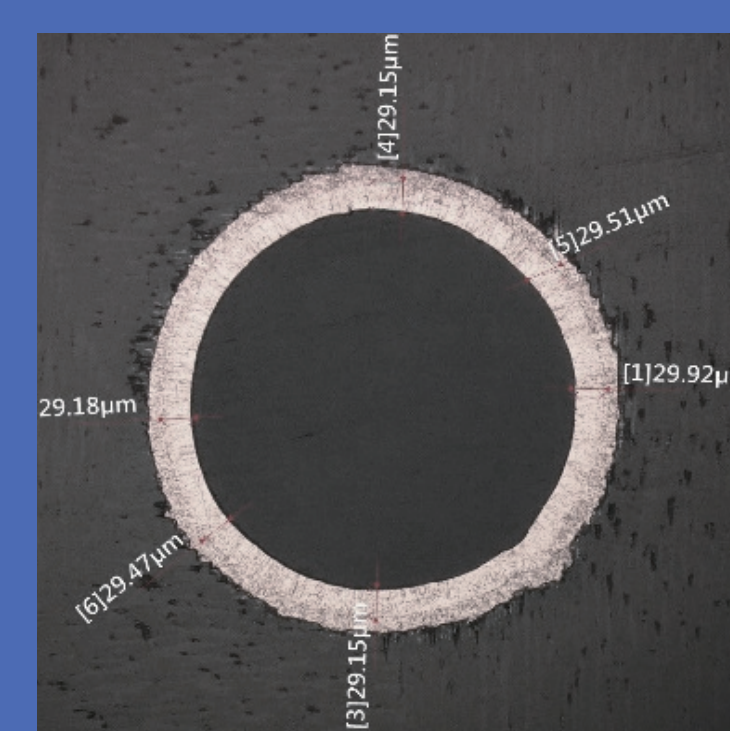
细致电镀晶格

Fine crystal structure



孔内铜厚均匀

Uniform deposition



THK 3.2mm  
under 2.5 ASD

## 应用领域 Application

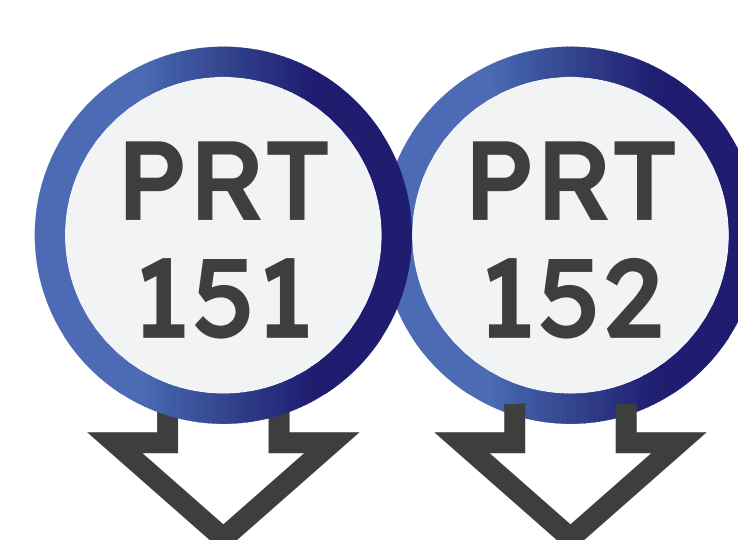
高层数PCB厚板

High layer count PCB

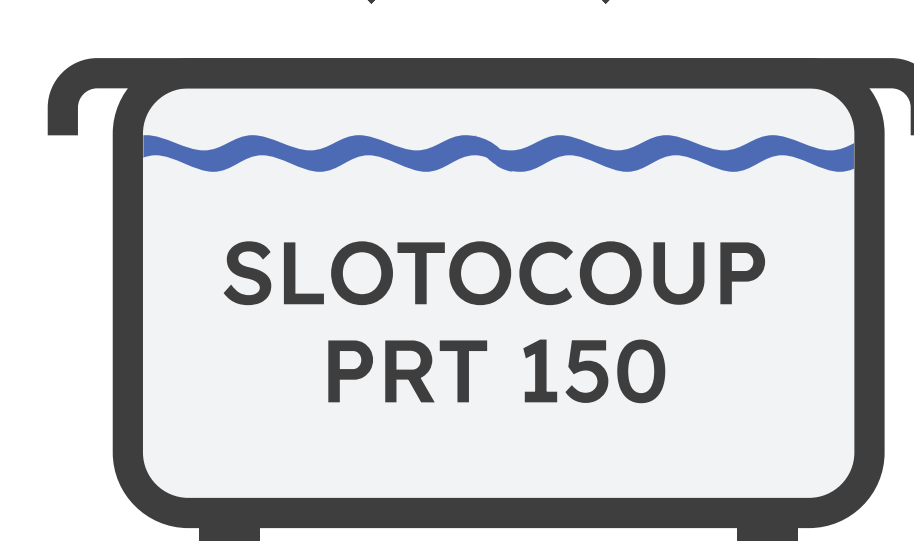
高速伺服器及通讯伺服器主板

Hyper speed server and communication server

## CO<sub>2</sub> 足迹 CO<sub>2</sub> Footprint



Carbon Footprint for Minimal vs. Maximal Chemistry Consumption



0.69-2.77kg CO<sub>2</sub>/10 kAh